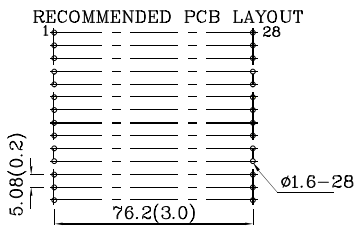
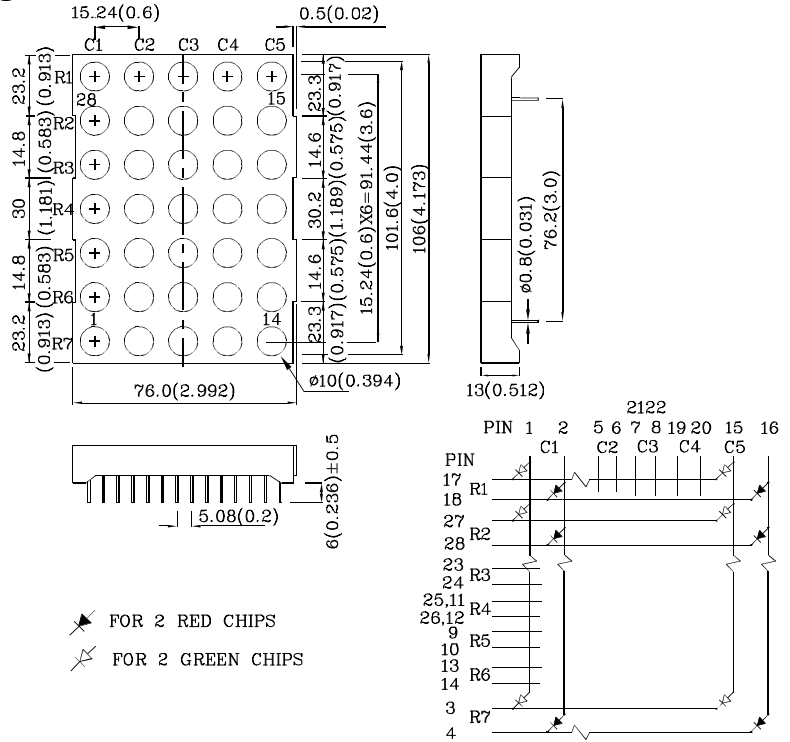


**Features**

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white dots
- Optional black face provides superior color contrast
- RoHS Compliant



**Package Schematics**



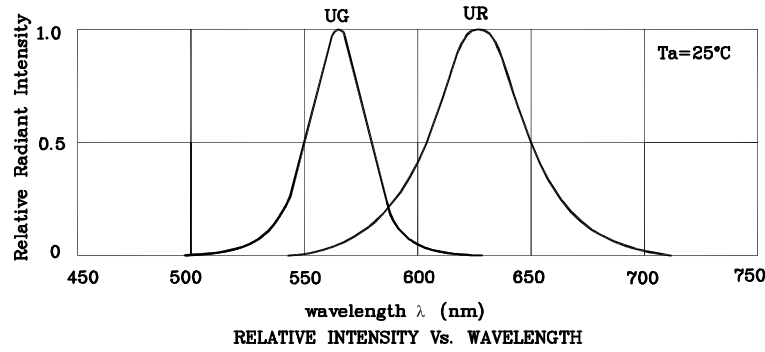
**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.

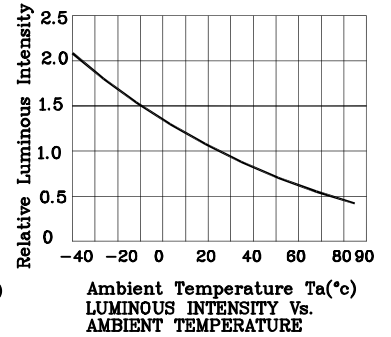
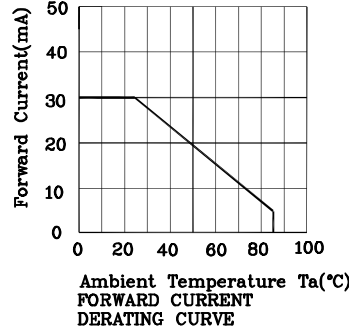
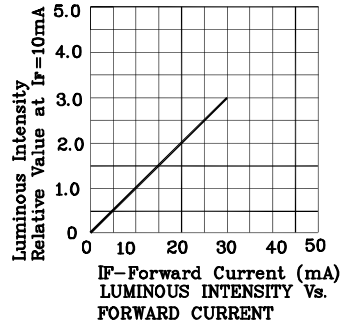
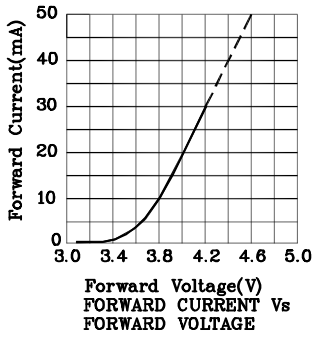
| Absolute Maximum Ratings<br>( $T_A=25^\circ\text{C}$ )   |                       | UR<br>(GaAsP/<br>GaP) | UG<br>(GaP) | Unit |
|--|-----------------------|-----------------------|-------------|------|
| Reverse Voltage<br>Per Segment or (Dp and Comma)   | $V_R$                 | 5                     | 5           | V    |
| Forward Current<br>Per Segment or (Dp and Comma)   | $I_F$                 | 30                    | 25          | mA   |
| Forward Current (Peak)<br>Per Segment or (Dp and Comma)<br>1/10Duty Cycle<br>0.1ms Pulse Width | $i_{FS}$              | 160                   | 140         | mA   |
| Power Dissipation<br>Per Segment or (Dp and Comma)   | $P_D$                 | 150                   | 125         | mW   |
| Operating Temperature  | $T_A$                 | -40 ~ +85             |             | °C   |
| Storage Temperature  | $T_{stg}$             | -40 ~ +85             |             |      |
| Lead Solder Temperature<br>[2mm Below Package Base]  | 260°C For 3~5 Seconds |                       |             |      |

| Operating Characteristics<br>( $T_A=25^\circ\text{C}$ )                          |                 | UR<br>(GaAsP/GaP) | UG<br>(GaP) | Unit          |
|--|-----------------|-------------------|-------------|---------------|
| Forward Voltage (Typ.)<br>Per Segment or (Dp and Comma)<br>( $I_F=10\text{mA}$ ) | $V_F$           | 3.8               | 4           | V             |
| Forward Voltage (Max.)<br>Per Segment or (Dp and Comma)<br>( $I_F=10\text{mA}$ ) | $V_F$           | 5                 | 5           | V             |
| Reverse Current (Max.)<br>( $V_R=5\text{V}$ )                                    | $I_R$           | 10                | 10          | $\mu\text{A}$ |
| Wavelength of Peak<br>Emission (Typ.)<br>( $I_F=10\text{mA}$ )                   | $\lambda_P$     | 627               | 565         | nm            |
| Wavelength of Dominant<br>Emission (Typ.)<br>( $I_F=10\text{mA}$ )               | $\lambda_D$     | 625               | 568         | nm            |
| Spectral Line Full Width<br>At Half-Maximum (Typ.)<br>( $I_F=10\text{mA}$ )      | $\Delta\lambda$ | 45                | 30          | nm            |
| Capacitance (Typ.)<br>( $V_F=0\text{V}$ , $f=1\text{MHz}$ )                      | C               | 15                | 15          | pF            |

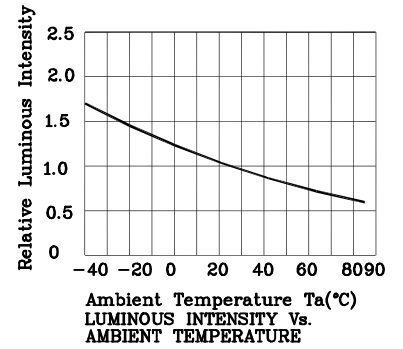
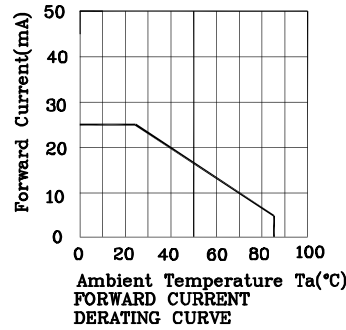
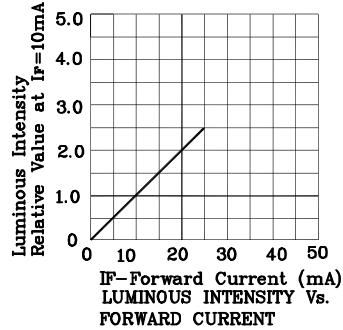
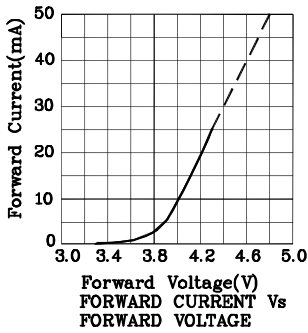
| Part Number  | Emitting Color | Emitting Material | Luminous Intensity<br>( $I_F=10\text{mA}$ )<br>ucd |       | Wavelength<br>nm<br>$\lambda_P$ | Description  |
|--------------|----------------|-------------------|--|-------|---------------------------------|--------------|
|              |                |                   | min.   | typ.  |                                 |              |
| XMURG100A-1A | Red            | GaAsP/GaP         | 14000  | 25990 | 627                             | Column Anode |
|              | Green          | GaP               | 21000  | 41990 | 565                             |              |



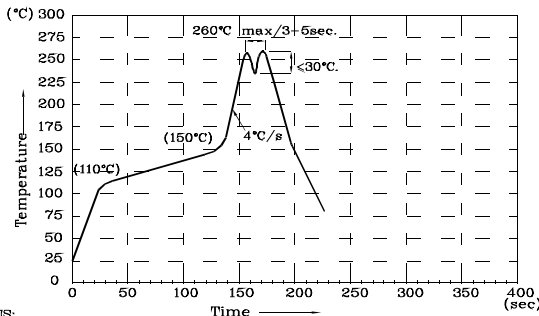
❖ UR



❖ UG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

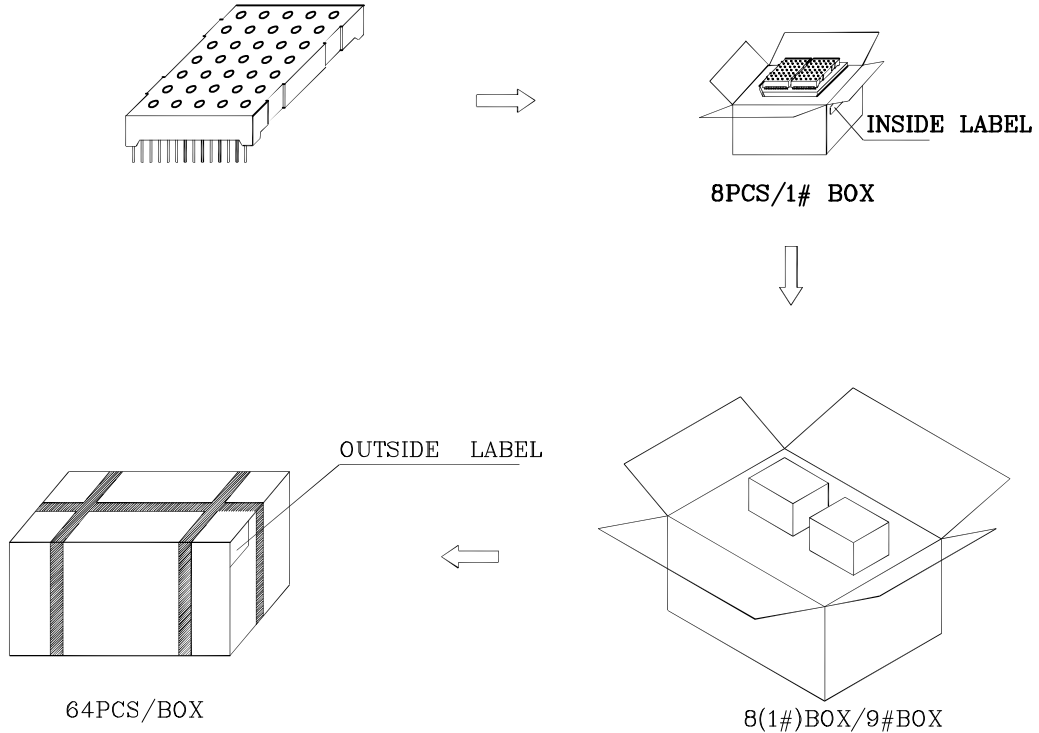
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

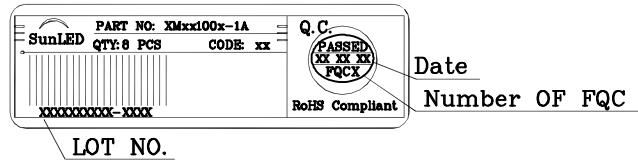
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside LABEL On 1#BOX



Outside LABEL On Box

